Amendments to the Specification

Please replace paragraph [0105] with the following amended paragraph:

[0105] A first embodiment of the semiconductor device manufacturing equipment will now be described with reference to Figs. 3, 6 and 7. The semiconductor device manufacturing equipment comprises a housing and a plurality of main process chambers 32a, a plurality of load lock chambers 34a, and a plurality of auxiliary process chambers 36a, and a transfer chamber 30a disposed in the housing. As shown in Figs. 3 and 7, the transfer chamber 30a is in the form of a rectangular parallelepiped having first and second sides located directly across from each other. The first and second sides of the transfer chamber 30a extend in planes, respectively, that are parallel to one another. Also ~~Of these respective working chambers~~, the main process, load lock and auxiliary process chambers 32a, 34a, and 36a are arrayed vertically, as best shown in Figs. 6 and 7. More specifically, the process chambers 32a, 36a are disposed in a vertical array at one side of the transfer chamber 30a, whereas the load lock chambers 34a are disposed in a vertical array at the other side of the transfer chamber 30a. A number of the load lock chambers 34a are disposed side-by-side as oriented parallel to one another and spaced relative to each other in a first axial direction on at least one of such levels. The first axial direction lies parallel to the planes in which the first and second sides of the transfer chamber 30a lie (Fig. 3). Similarly, some of the process chambers 32a are disposed at a plurality of levels, respectively, at the second side of the transfer chamber 30a , and

a number of the process chambers 32a are disposed side-by-side as oriented parallel to one another and spaced relative to each other in the first axial direction. The chambers are also connected to the transfer chamber 30a of the semiconductor device manufacturing equipment independently of each other through respective doors 22b and 22c (FIG. 3) . Doors 22a connect the load lock chambers 34a to the environment outside the equipment.

Please replace paragraph [0110] with the following amended paragraph:

[0110] The robot Ra having a robot arm is disposed in the transfer chamber 30 for positioning the wafers W relative to and transferring the wafers W between the respective working chambers 32a, 34a and 36a. As shown by the arrows in Figs. 3 and 7, the robot arm is supported so as to be independently linearly translatable in the first axial direction in which respective ones of the load lock chambers 34a (or corresponding main process chambers 32a) are disposed side-by-side, linearly translatable in a vertical direction, rotatable about a vertical axis. The terminal end of the robot arm comprises wafer support member 18 for supporting (e.g., grasping) a wafer W as the wafer W is being transferred by the robot Ra. As shown by double-headed arrows in Figs. 3 and 7, the wafer support member 18 is supported by the robot arm so as to be extendable and retractable independently of the robot arm.